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AOTF404 N-Channel Enhancement Mode Field Effect Transistor

General Description

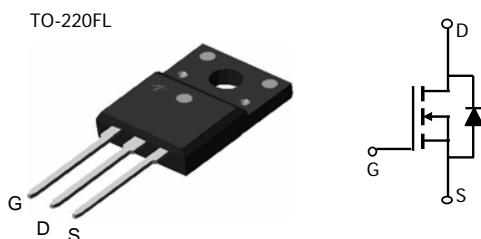
The AOTF404/L uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in high voltage synchronous rectification, load switching and general purpose applications.

- RoHS Compliant
- AOTF404L Halogen Free

Features

V_{DS} (V) = 105V
 I_D = 26 A ($V_{GS} = 10V$)
 $R_{DS(ON)} < 28 \text{ m}\Omega$ ($V_{GS} = 10V$)
 $R_{DS(ON)} < 31 \text{ m}\Omega$ ($V_{GS} = 6V$)

100% UIS Tested!



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Maximum | Units |
|---|----------------|-------------------------|------------------|
| Drain-Source Voltage | V_{DS} | 105 | V |
| Gate-Source Voltage | V_{GS} | ± 25 | V |
| Continuous Drain Current | I_D | $T_C=25^\circ\text{C}$ | 26 |
| | | $T_C=100^\circ\text{C}$ | 18 |
| Pulsed Drain Current ^C | I_{DM} | 90 | A |
| Continuous Drain Current | I_{DSM} | $T_A=25^\circ\text{C}$ | 5.8 |
| | | $T_A=70^\circ\text{C}$ | 4.5 |
| Avalanche Current ^C | I_{AR} | 37 | A |
| Repetitive avalanche energy $L=0.1\text{mH}$ ^C | E_{AR} | 68 | mJ |
| Power Dissipation ^B | P_D | $T_C=25^\circ\text{C}$ | 43 |
| | | $T_C=100^\circ\text{C}$ | 21 |
| Power Dissipation ^A | P_{DSM} | $T_A=25^\circ\text{C}$ | 2.2 |
| | | $T_A=70^\circ\text{C}$ | 1.38 |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 175 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|--|-----------------|--------------|------|--------------------|
| Maximum Junction-to-Ambient ^A | $R_{\theta JA}$ | 10 | 12 | $^\circ\text{C/W}$ |
| Maximum Junction-to-Ambient ^{A,D} | | Steady-State | 48.5 | 58 |
| Maximum Junction-to-Case ^B | $R_{\theta JC}$ | 2.9 | 3.5 | $^\circ\text{C/W}$ |

AOTF404

Electrical Characteristics (T_J=25°C unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------------------------|---------------------------------------|---|------|------|--------|-------|
| STATIC PARAMETERS | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | I _D =10mA, V _{GS} =0V | 105 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =105V, V _{GS} =0V T _J =55°C | | | 1 5 | μA |
| I _{GSS} | Gate-Body leakage current | V _{DS} =0V, V _{GS} =±25V | | | 100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 2.5 | 3.2 | 4 | V |
| I _{D(ON)} | On state drain current | V _{GS} =10V, V _{DS} =5V | 90 | | | A |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =20A | | 21 | 28 | mΩ |
| | | T _J =125°C | | 39 | 47 | |
| | | V _{GS} =6V, I _D =20A | | 23.5 | 31 | mΩ |
| g _{FS} | Forward Transconductance | V _{DS} =5V, I _D =20A | | 73 | | S |
| V _{SD} | Diode Forward Voltage | I _S =1A, V _{GS} =0V | | 0.72 | 1 | V |
| I _S | Maximum Body-Diode Continuous Current | | | | 55 | A |
| DYNAMIC PARAMETERS | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =25V, f=1MHz | 1630 | 2038 | 2445 | pF |
| C _{oss} | Output Capacitance | | 142 | 204 | 265 | pF |
| C _{riss} | Reverse Transfer Capacitance | | 51 | 85 | 119 | pF |
| R _g | Gate resistance | V _{GS} =0V, V _{DS} =0V, f=1MHz | 0.65 | 1.3 | 1.95 | Ω |
| SWITCHING PARAMETERS | | | | | | |
| Q _g (10V) | Total Gate Charge | V _{GS} =10V, V _{DS} =50V, I _D =20A | 30.8 | 38.5 | 46 | nC |
| Q _{gs} | Gate Source Charge | | 6.4 | 8 | 9.6 | nC |
| Q _{gd} | Gate Drain Charge | | 8 | 10 | 14 | nC |
| t _{D(on)} | Turn-On DelayTime | V _{GS} =10V, V _{DS} =50V, R _L =2.7Ω, R _{GEN} =3Ω | | 12.7 | | ns |
| t _r | Turn-On Rise Time | | | 8.2 | | ns |
| t _{D(off)} | Turn-Off DelayTime | | | 31.5 | | ns |
| t _f | Turn-Off Fall Time | | | 11.2 | | ns |
| t _{rr} | Body Diode Reverse Recovery Time | I _F =20A, dI/dt=500A/μs | 34 | 49 | 64 | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | I _F =20A, dI/dt=500A/μs | 337 | 481 | 625 | nC |

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B: The power dissipation P_D is based on T_{J(MAX)}=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=175°C.

D: The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C.

G: The maximum current rating is limited by bond-wires.

H: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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AOTF404

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

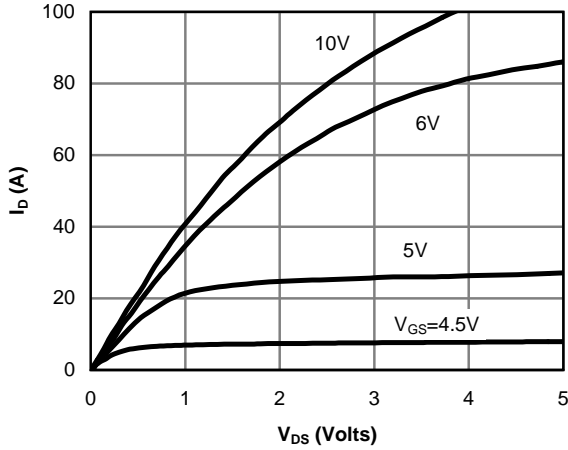


Fig 1: On-Region Characteristics

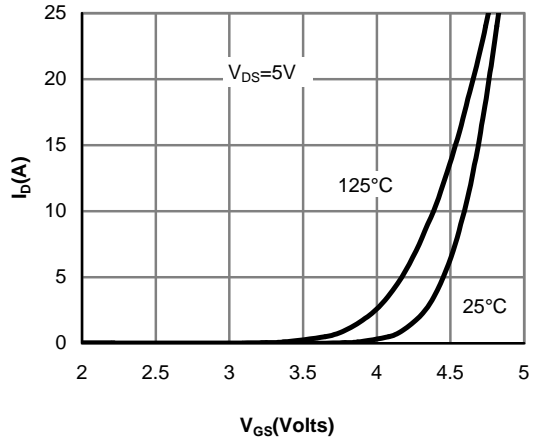


Figure 2: Transfer Characteristics

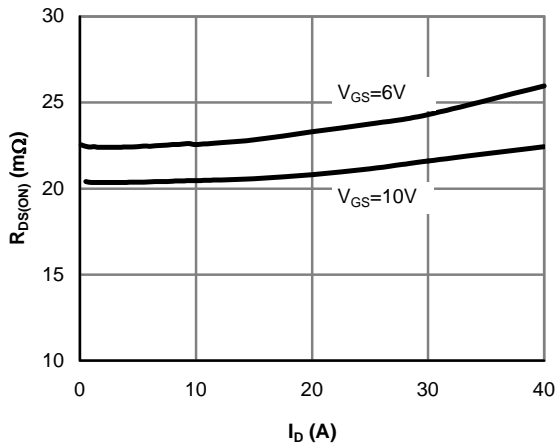


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

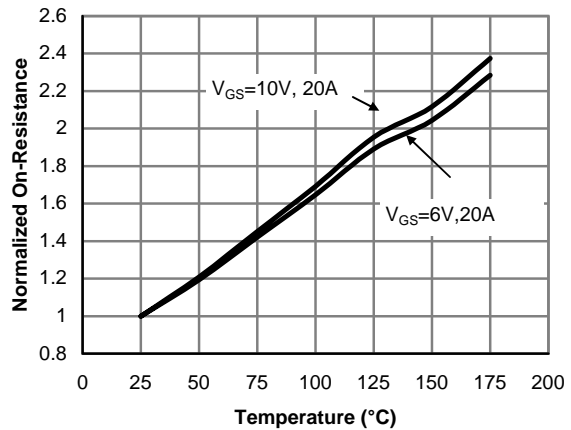


Figure 4: On-Resistance vs. Junction Temperature

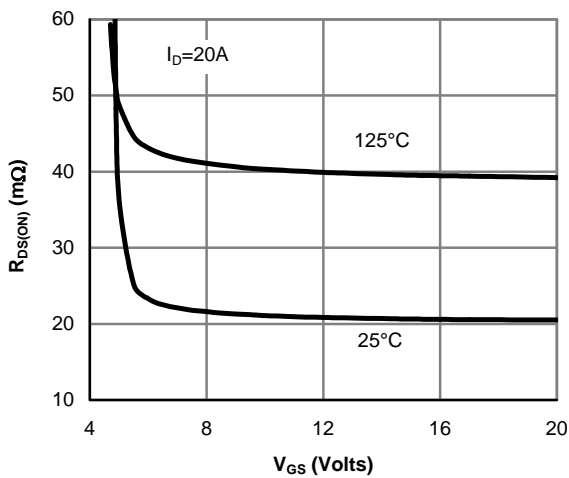


Figure 5: On-Resistance vs. Gate-Source Voltage

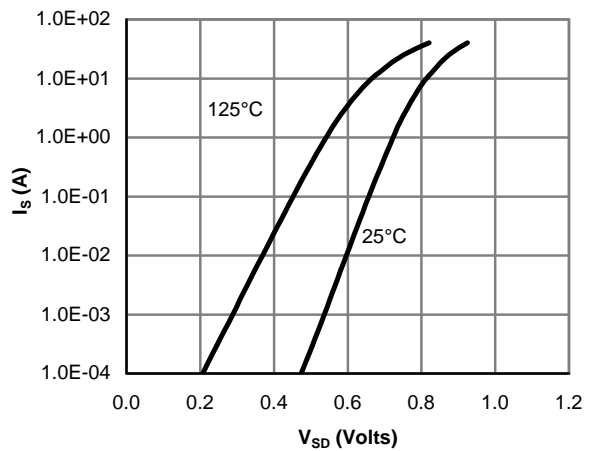


Figure 6: Body-Diode Characteristics

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

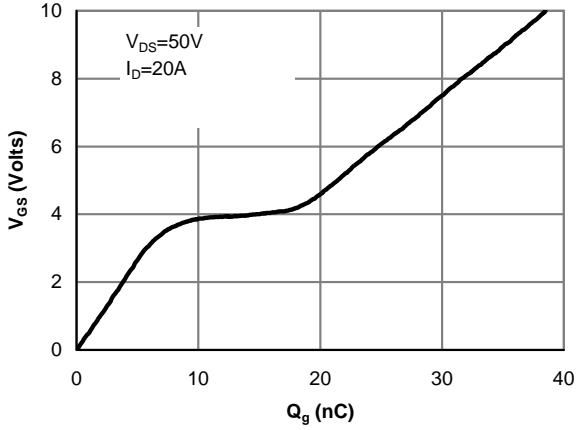


Figure 7: Gate-Charge Characteristics

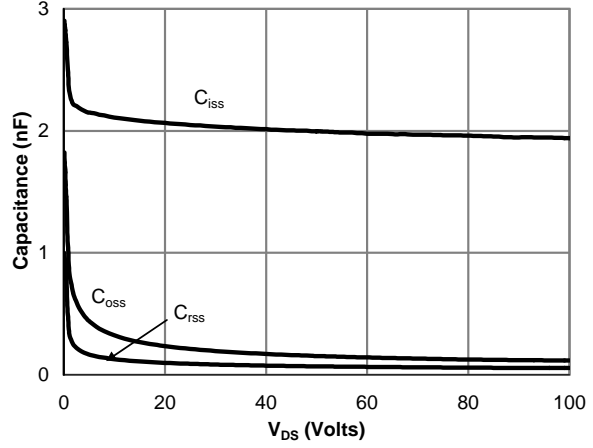


Figure 8: Capacitance Characteristics

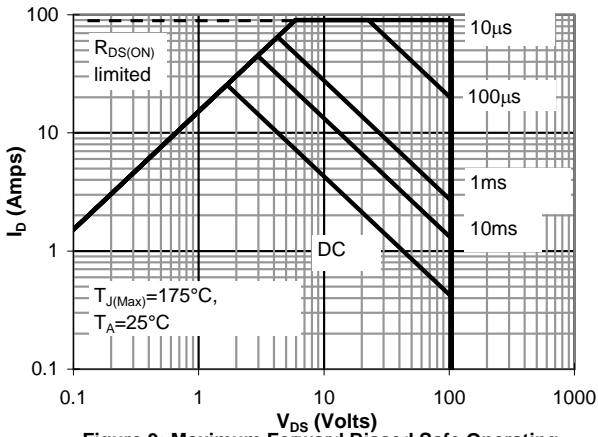


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

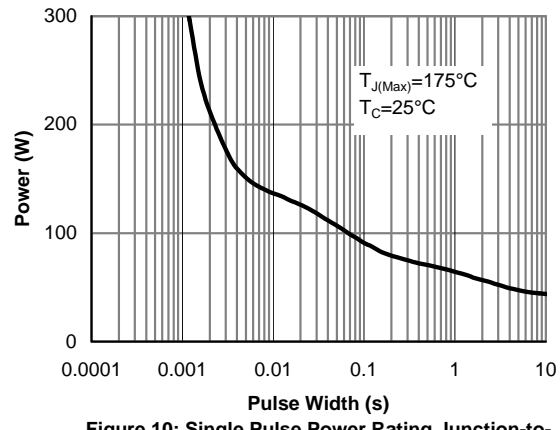


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

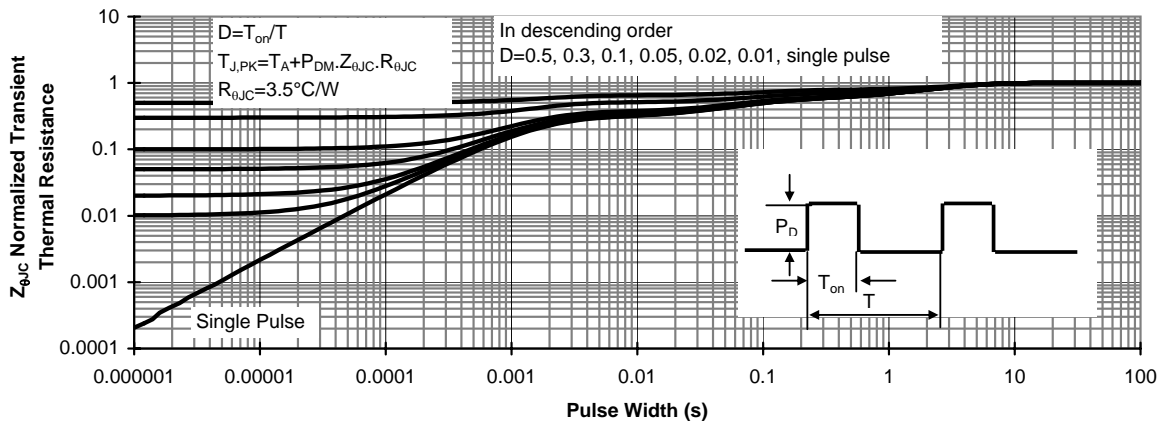


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

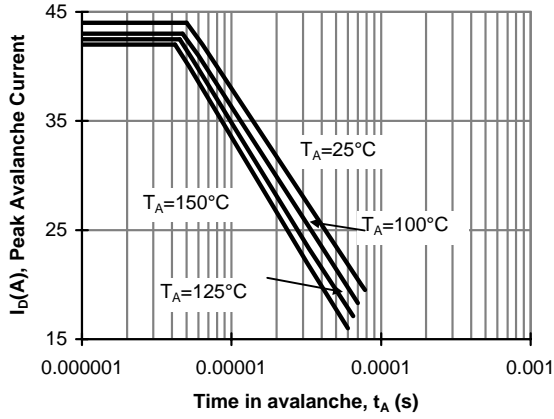


Figure 12: Single Pulse Avalanche capability

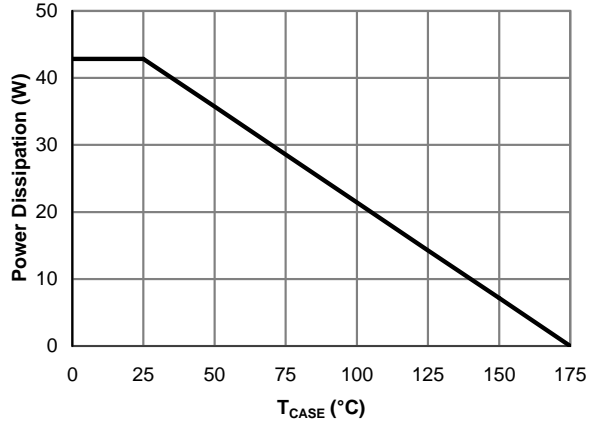


Figure 13: Power De-rating (Note B)

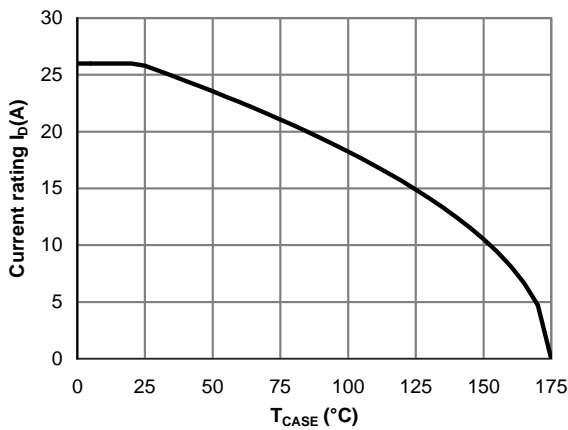


Figure 14: Current De-rating (Note B)

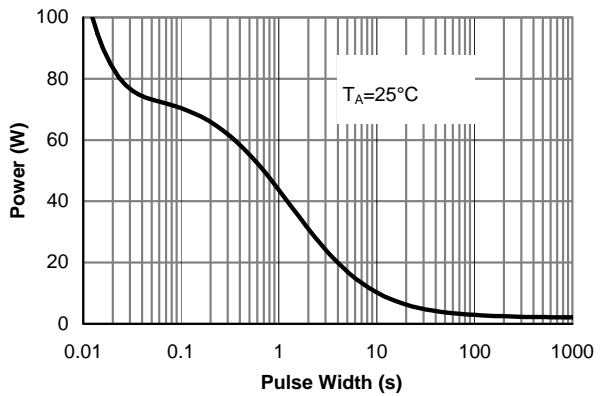


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

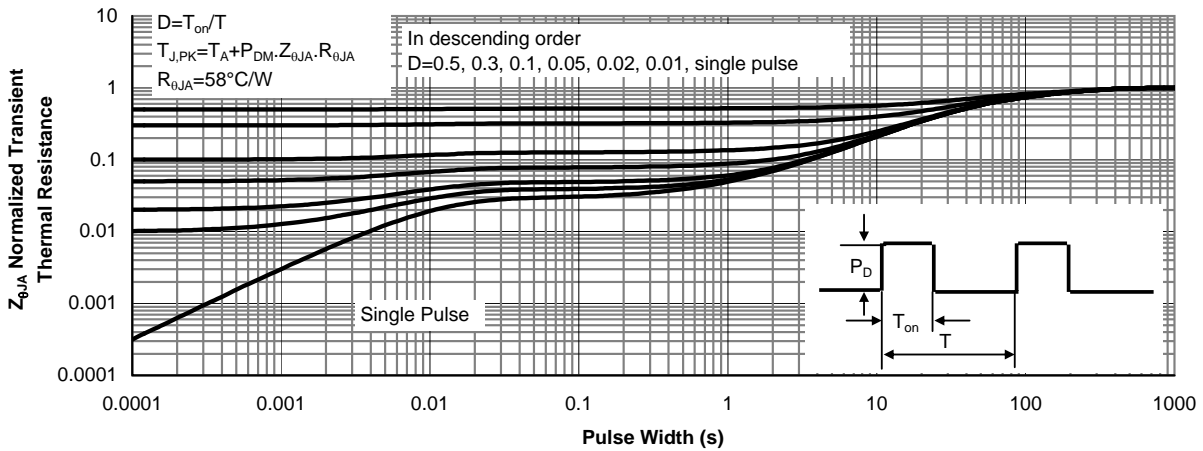
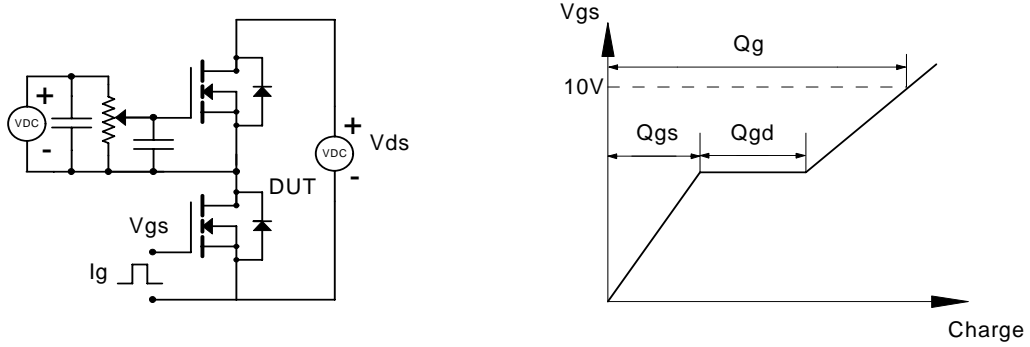


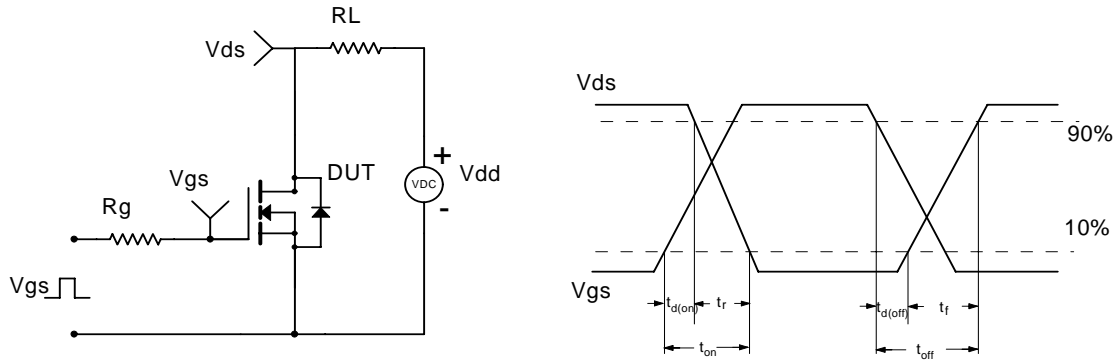
Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

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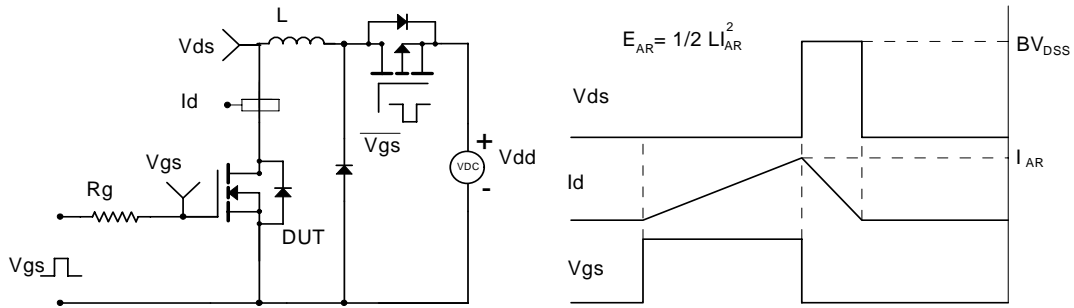
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

